

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No. 09/899,871
Confirmation No. 3335

I hereby certify that this correspondence is being transmitted to the United States Patent & Trademark Office via electronic submission or facsimile on the date indicated below:

10/27/2006 /Pamela Gerik/
Date Pamela Gerik

REQUEST FOR CORRECTED PATENT

Dear Sir:

Transmitted herewith is Form PTO-1050 which describes errors occurring in Patent No. 7,014,552 issued March 21, 2006. The errors are due to Patent Office oversights. Specifically, claims 10, 23, 24, 27, and 28 (claim numbers as referenced during prosecution) were not printed in the issued patent. Such claims were allowed during prosecution of the captioned application (*See, e.g.*, Advisory Action Mailed July 15, 2004; and Decision on Appeal Mailed March 23, 2005 -- page 1). In addition, claim 11 (claim 9 in the issued patent) was printed with additional text not included in the claim when allowed (*See, e.g.*, Supplemental Appeal Brief filed August 16, 2004; Decision on Appeal Mailed March 23, 2005).

It is respectfully requested that a corrected patent be issued pursuant to 37 C.F.R. § 1.322(b). Applicants believe no fees are required, however, should any fees be required, please deduct them from deposit account number 50-3268.

Respectfully submitted,
/Mollie E. Lettang/
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Reg. No. 48,405
Agent for Applicant(s)

Customer 35617
Date: October 27, 2006

UNITED STATES PATENT AND TRADEMARK OFFICE

CERTIFICATE OF CORRECTION

PATENT NO. 7,014,552

DATED: Mar. 21, 2006

INVENTOR(S): Collier et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the Claims:

Please add the following claims which were allowed during prosecution of the patent application, but were mistakenly omitted from the printed patent:

Claim 19. (original claim 10) The system of claim 1, wherein the spray element is adapted to be removed from the system.

Claim 20. (previously presented claim 23) A method for polishing multiple semiconductor topographies, comprising:

moving a polishing pad with respect to a semiconductor topography and a spray element;

polishing the semiconductor topography by positioning it against the moving polishing pad;

measuring an amount of matter adhered to the polishing pad subsequent to said polishing;

spraying a pressurized fluid from the spray element upon the polishing pad while moving the polishing pad, wherein said spraying is conducted based upon the amount of matter measured; and

removing matter adhered to the polishing pad.

Claim 21. (previously presented claim 24) The method of claim 20, further comprising polishing one or more additional topographies prior to said measuring.

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PATENT NO. 7,014,552

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CERTIFICATE OF CORRECTION

PATENT NO. 7,014,552

DATED: Mar. 21, 2006

INVENTOR(S): Collier et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the Claims:

Please add the following claims which were allowed during prosecution of the patent application, but were mistakenly omitted from the printed patent:

Claim 22. (previously presented claim 22) The method of claim 14, wherein said spraying is conducted simultaneously with polishing one or more semiconductor topographies with the polishing system.

Claim 23. (original claim 28) The method of claim 21, further comprising applying a polishing fluid from a dispense component prior to said polishing.

Col. 18

lines 22-23: please delete the text "and configured to move independent of an arm comprising the nozzles" since this phrase was not included in the claim when allowed.

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